



Electrical Lab.

**ASE Group Kaohsiung** 

Sep. 10, 2019



# **Outline**

#### LPDDR4

- SI Part
- PI Part
- AR
- LPDDR4X
  - SI Part
  - PI Part



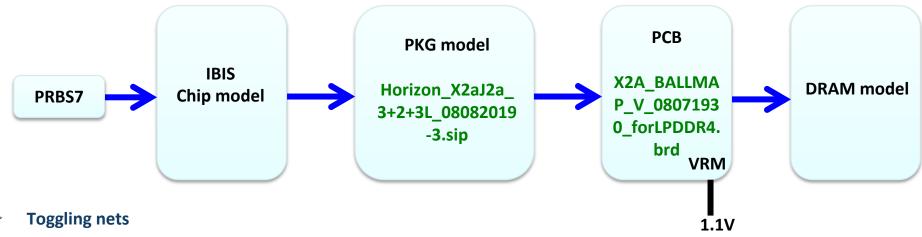


# LPDDR4





#### **Write mode Schematic**



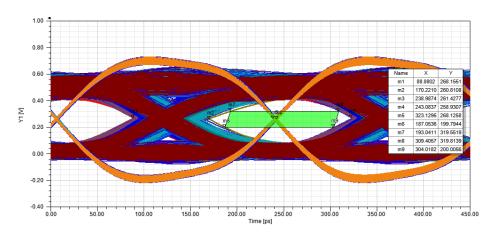
- Byte 1: DRAM\_DATA1\_A ~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A
- Byte 2: DRAM\_DATA8\_A ~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A
- Byte 3: DRAM\_DATA1\_B ~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B
- Byte 4: DRAM\_DATA8\_B ~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B
- > CA 1: DRAM CAO A ~ DRAM CA5 A, DRAM NCSO A, DRAM NCS1 A, DRAM CK C A, DRAM CK T A
- > CA\_2: DRAM\_CA0\_B ~ DRAM\_CA5\_B, DRAM\_NCS0\_B, DRAM\_NCS1\_B, DRAM\_CK\_C\_B, DRAM\_CK\_T\_B
- Chip model: dwc\_ddrphy\_txrxdq\_ns\_clipped\_lpd4.ibs, dwc\_ddrphy\_txrxdqs\_ns\_clipped\_lpd4.ibs, dwc\_ddrphy\_txrxca\_ns\_clipped\_lpd4.ibs
  - DQ: mal4drv27 dl4 40
  - DQS: mal4drv27 dl4 40
  - > CA: mal4drv27 dl4 40
  - CLK: mal4drv27\_dl4\_40
- > On-die decap: 3.6nF & 4.4mohm
- > DRAM model: z11m 1p1v at.ibs
  - DQ IN ODT40 VOH25 4266
- CA\_INPUT\_ODT40\_VOH25\_4266
- DQS\_IN\_ODT40\_VOH25\_4266
- CLK\_INPUT\_ODT40\_VOH25\_4266



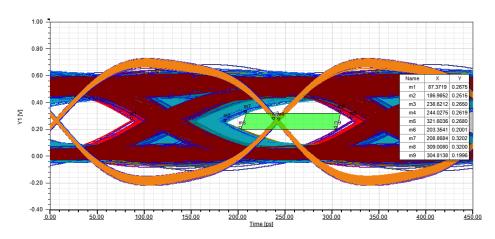


# **DQ Write Mode**

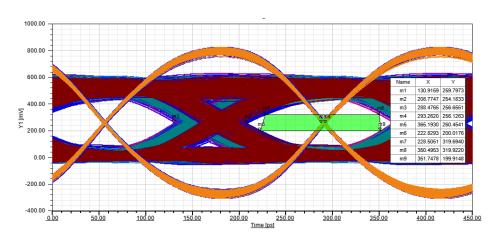
Vac & Vdc: 0.26 +/- 0.06V (320mv & 200mv)



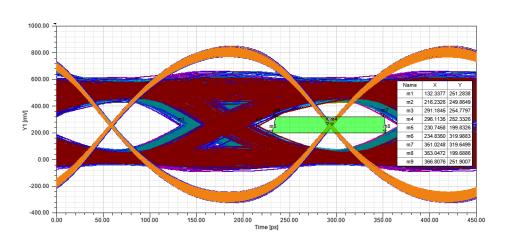
DRAM\_DATA1\_A~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A



DRAM\_DATA1\_B~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B



DRAM\_DATA8\_A~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A



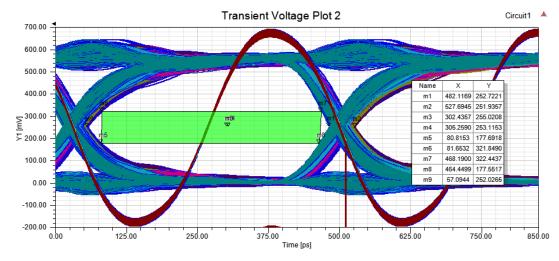
DRAM\_DATA8\_B~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B



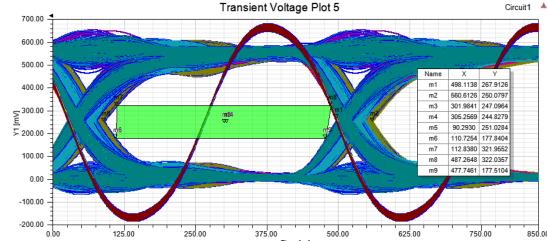


#### **CA Write Mode**

Vac & Vdc: 0.25 +/- 0.0725V (322.5mv & 177.5mv)



CA\_1: DRAM\_CA0\_A ~ DRAM\_CA5\_A, DRAM\_NCS0\_A, DRAM\_NCS1\_A, DRAM\_CK\_C\_A, DRAM\_CK\_T\_A



CA\_2: DRAM\_CA0\_B ~ DRAM\_CA5\_B, DRAM\_NCS0\_B, DRAM\_NCS1\_B, DRAM\_CK\_C\_B, DRAM\_CK\_T\_B



### **Write Mode Simulation Result**

#### **DQ Write Mode**

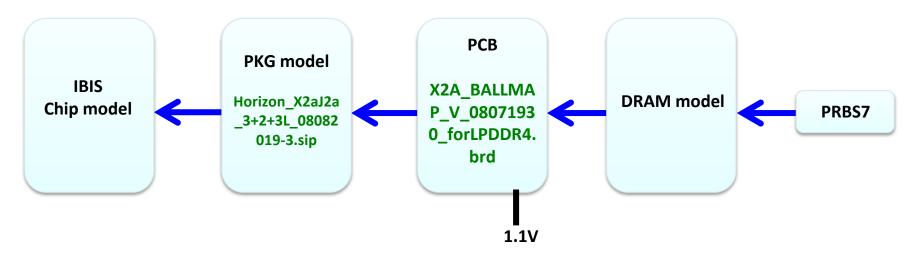
Items	Byte 1	Byte 2	Byte 3	Byte 4	SPEC
DQ Skew+Jitter (ps)	81	78	100	84	-
DQS Jitter (ps)	4	5	5	5	-
TdIPW_total (UI)	0.65	0.67	0.58	0.64	0.45
TdIVW_total (UI)	0.47	0.52	0.41	0.49	0.25

#### **CA Write Mode**

Items CA_1		CA_2	SPEC	
CA Skew+Jitter (ps)	46	63	-	
CLK Jitter (ps)	3	3	-	
TcIPW_total (UI)	0.91	0.87	0.6	
TcIVW_total (UI)	0.81	0.78	0.3	



### **Read mode Schematic**



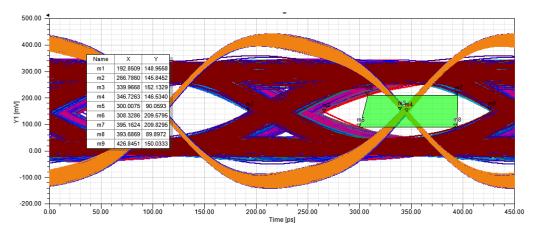
- Toggling nets
  - Byte 1: DRAM\_DATA1\_A ~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A
  - Byte 2: DRAM\_DATA8\_A ~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A
  - Byte 3: DRAM\_DATA1\_B ~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B
  - Byte 4: DRAM\_DATA8\_B ~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B
- > Chip model: dwc\_ddrphy\_txrxdq\_ns\_clipped\_lpd4.ibs, dwc\_ddrphy\_txrxdqs\_ns\_clipped\_lpd4.ibs
  - DQ : mal4drv27\_dl4\_odt40
  - DQS: mal4drv27 dl4 odt40
- > On-die decap: 3.6nF & 4.4mohm
- > DRAM model : z11m\_1p1v\_at.ibs
  - DQ PD40 ODTDIS VOH25 4266
  - DQS\_PD40\_ODTDIS\_VOH25\_4266



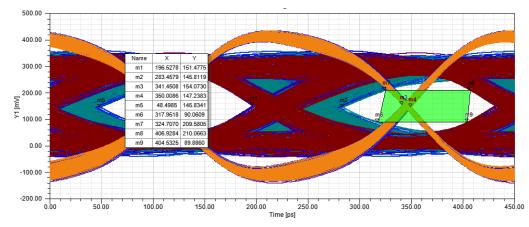


# **DQ Read Mode**

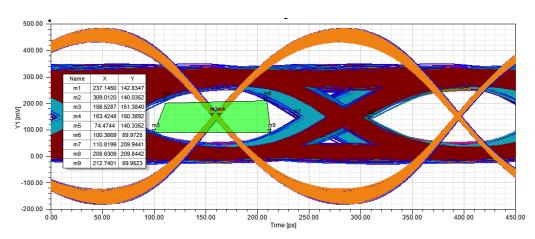
Vac & Vdc: 0.15 +/- 0.06V (210mv & 90mv)



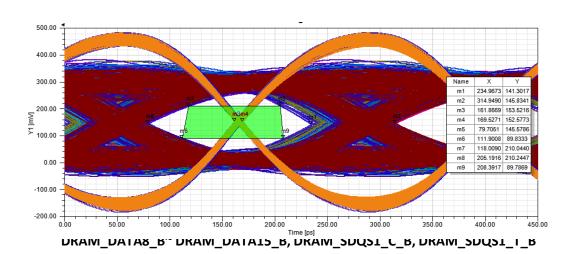
DRAM\_DATA1\_A~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A



DRAM\_DATA1\_B~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B



DRAM\_DATA8\_A~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A





### **Read Mode Simulation Result**

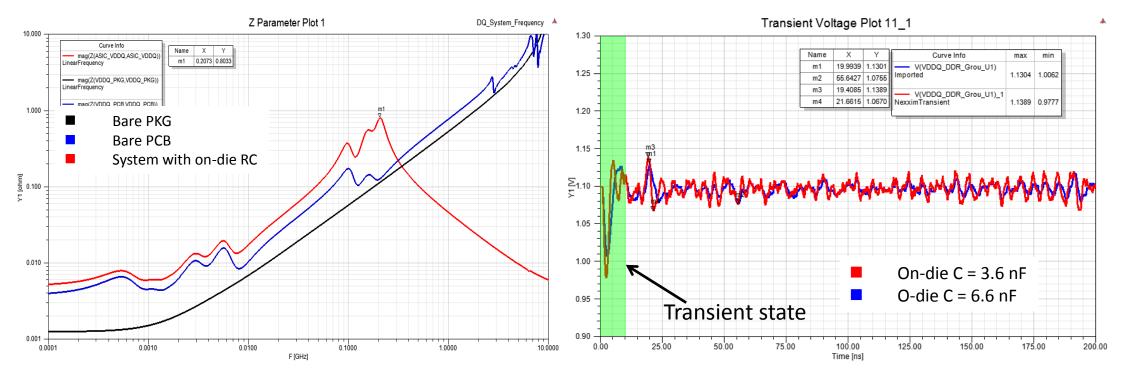
#### **DQ Read Mode**

Items	Byte 1	Byte 2	Byte 3	Byte 4	SPEC
DQ Skew+Jitter (ps)	73	72	86	80	-
DQS Jitter (ps)	7	7	9	8	-
TdIPW_total (UI)	0.68	0.7	0.63	0.66	0.45
TdIVW_total (UI)	0.37	0.41	0.35	0.37	0.25





# VDDQ\_DDR



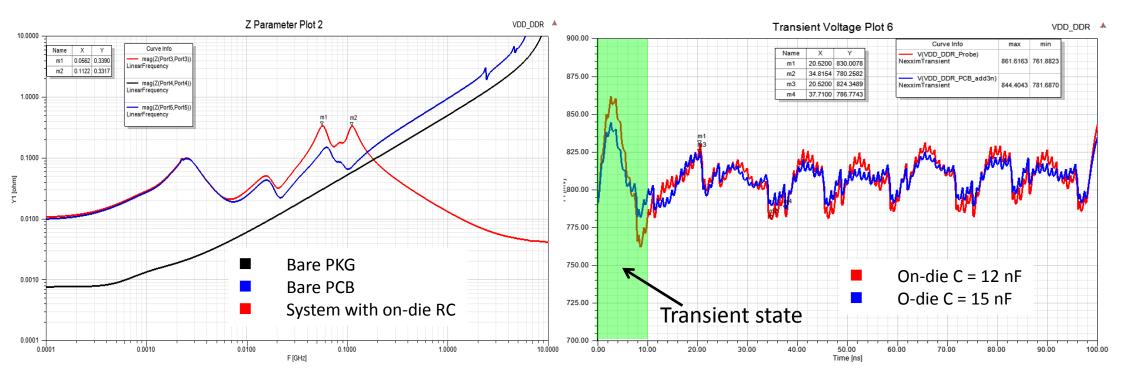
- Transient state (0 ~ 10ns):
  - On-die C => 3.6 nF: P2P Noise = 2.3% ~ -11%
  - On-die C => 6.6 nF: P2P Noise = 2.1% ~ -8.5%
- Steady state (10 ~ 200ns):
  - On-die C => 3.6nF: P2P Noise = 3% ~ -3%
  - On-die C => 6.6nF: P2P Noise = 2.7% ~ -2.3%

• SPEC: +/- 2.5% noise





# VDD\_DDR



- Transient state  $(0 \sim 10 \text{ns})$ :
  - On-die C => 12 nF: P2P Noise = 7.6% ~ -4.75%
  - On-die C => 15 nF: P2P Noise = 5.5% ~ -2.3%
- Steady state (10 ~ 200ns):
  - On-die C => 12 nF: P2P Noise = 3.8% ~ -2.5%
  - On-die C => 15 nF: P2P Noise = 3% ~ -1.6%

• SPEC: +/- 2% noise



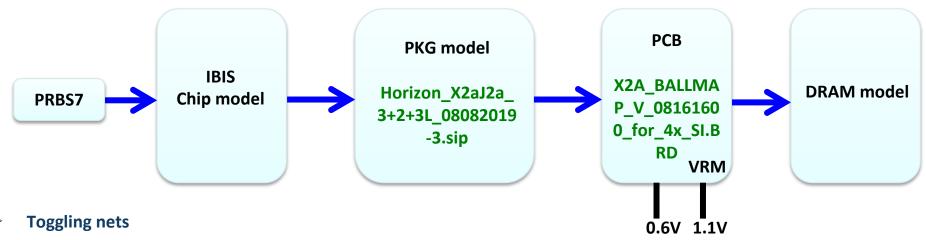


# LPDDR4X





#### **Write mode Schematic**



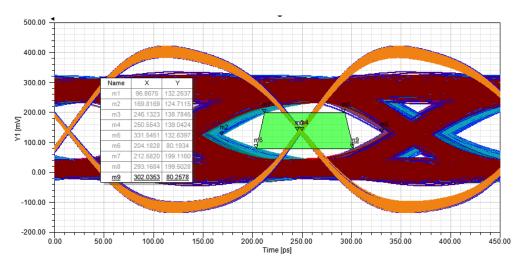
- Byte 1: DRAM\_DATA1\_A ~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A
- > Byte 2: DRAM\_DATA8\_A ~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A
- Byte 3: DRAM\_DATA1\_B ~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B
- Byte 4: DRAM\_DATA8\_B ~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B
- CA\_1: DRAM\_CA0\_A ~ DRAM\_CA5\_A, DRAM\_NCS0\_A, DRAM\_NCS1\_A, DRAM\_CK\_C\_A, DRAM\_CK\_T\_A
- > CA\_2: DRAM\_CA0\_B ~ DRAM\_CA5\_B, DRAM\_NCS0\_B, DRAM\_NCS1\_B, DRAM\_CK\_C\_B, DRAM\_CK\_T\_B
- Chip model: dwc\_ddrphy\_txrxdq\_ns\_clipped\_lpd4x.ibs, dwc\_ddrphy\_txrxdqs\_ns\_clipped\_lpd4x.ibs, dwc\_ddrphy\_txrxca\_ns\_clipped\_lpd4x.ibs
  - DQ: mal4drv27 dl4x 40
  - DQS: mal4drv27 dl4x 40
  - > CA: mal4drv27 dl4x 40
  - CLK: mal4drv27\_dl4x\_40
- > On-die decap: 1nF & 24mohm, 3.6nF & 4.4mohm
- > DRAM model: z11m Op6v at.ibs
  - > DQ IN ODT40 VOH60 4266
- CA INPUT ODT40 VOH60 4266
- DQS IN ODT40 VOH60 4266
- CLK\_INPUT\_ODT40\_VOH60\_4266



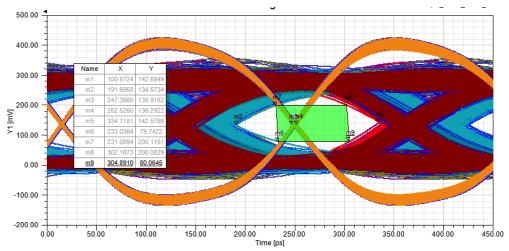


## **DQ Write Mode**

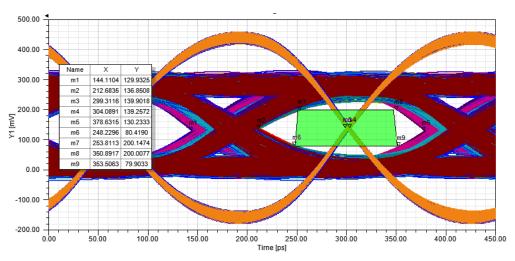
Vac & Vdc: 0.14 +/- 0.06V (200mv & 80mv)



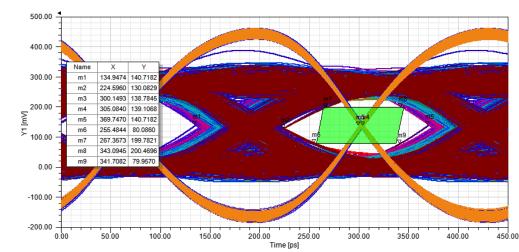
DRAM\_DATA1\_A~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A



DRAM\_DATA1\_B~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B



DRAM\_DATA8\_A~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A



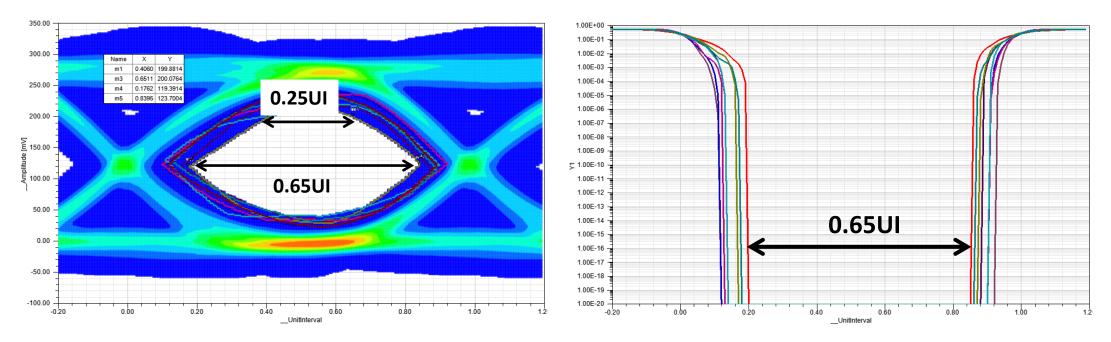
DRAM\_DATA8\_B~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B





# DQ Write Mode - Byte3 (stat.)

Vac & Vdc: 0.14 +/- 0.06V (200mv & 80mv)



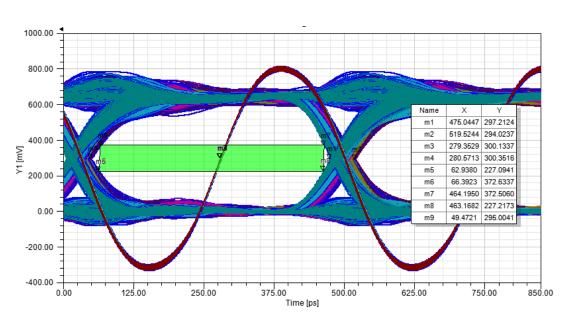
DRAM\_DATA1\_B~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B



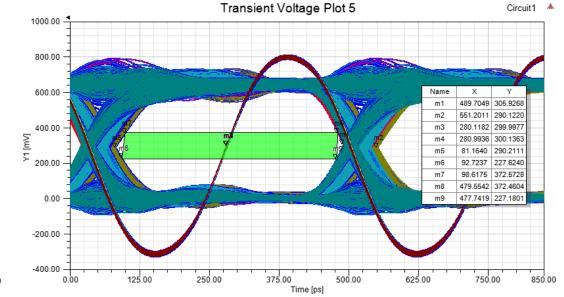


#### **CA Write Mode**

Vac & Vdc: 0.3 +/- 0.0725V (372.5mv & 227.5mv)



CA\_1: DRAM\_CAO\_A ~ DRAM\_CA5\_A, DRAM\_NCSO\_A, DRAM\_NCS1\_A, DRAM\_CK\_C\_A, DRAM\_CK\_T\_A



CA\_2: DRAM\_CA0\_B ~ DRAM\_CA5\_B, DRAM\_NCS0\_B, DRAM\_NCS1\_B, DRAM\_CK\_C\_B, DRAM\_CK\_T\_B





### **Write Mode Simulation Result**

#### **DQ Write Mode**

Items	Byte 1	Byte 2	Byte 3	Byte 3 (stat.)	Byte 4	SPEC
DQ Skew+Jitter (ps)	72	68	91	-	90	-
DQS Jitter (ps)	5	5	5	-	4	-
TdIPW_total (UI)	0.69	0.71	0.61	0.65	0.62	0.45
TdIVW_total (UI)	0.35	0.41	0.29	0.25	0.32	0.25

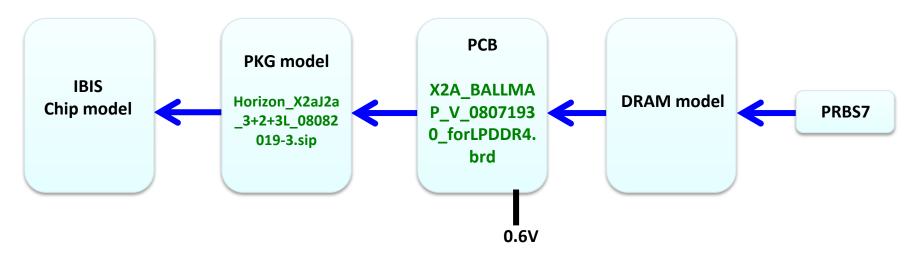
#### **CA Write Mode**

Items	CA_1	CA_2	SPEC
CA Skew+Jitter (ps)	45	61	-
CLK Jitter (ps)	1	1	-
TcIPW_total (UI)	0.91	0.87	0.6
TcIVW_total (UI)	0.85	0.82	0.3





### **Read mode Schematic**



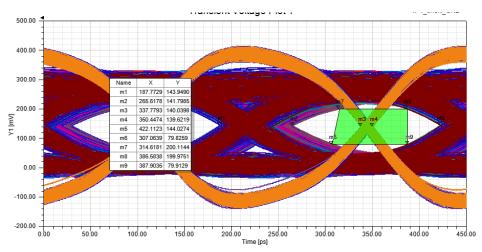
- Toggling nets
  - Byte 1: DRAM\_DATA1\_A ~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A
  - Byte 2: DRAM\_DATA8\_A ~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A
  - Byte 3: DRAM\_DATA1\_B ~ DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B
  - Byte 4: DRAM\_DATA8\_B ~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B
- > Chip model: dwc\_ddrphy\_txrxdq\_ns\_clipped\_lpd4x.ibs, dwc\_ddrphy\_txrxdqs\_ns\_clipped\_lpd4x.ibs
  - DQ: mal4drv27 dl4x odt40
  - DQS: mal4drv27\_dl4x\_odt40
- > On-die decap: 1nF & 24mohm
- DRAM model : z11m\_0p6v\_at.ibs
  - > DQ PD40 ODTDIS VOH60 4266
  - DQS\_PD40\_ODTDIS\_VOH60\_4266



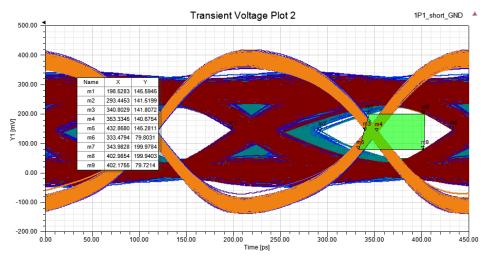


## **DQ Read Mode**

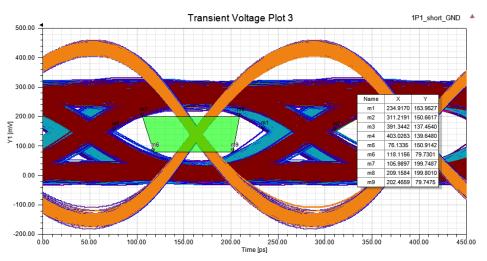
Vac & Vdc: 0.14 +/- 0.06V (200mv & 80mv)



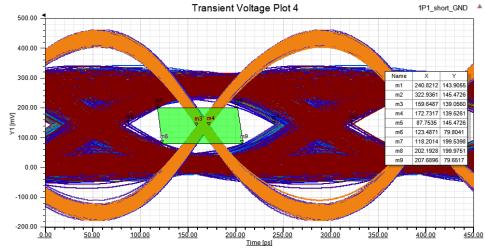
DRAM\_DATA1\_A~ DRAM\_DATA7\_A, DRAM\_SDQS0\_C\_A, DRAM\_SDQS0\_T\_A



DRAM\_DATA1\_B~DRAM\_DATA7\_B, DRAM\_SDQS0\_C\_B, DRAM\_SDQS0\_T\_B



DRAM\_DATA8\_A~ DRAM\_DATA15\_A, DRAM\_SDQS1\_C\_A, DRAM\_SDQS1\_T\_A



DRAM\_DATA8\_B~ DRAM\_DATA15\_B, DRAM\_SDQS1\_C\_B, DRAM\_SDQS1\_T\_B





### **Read Mode Simulation Result**

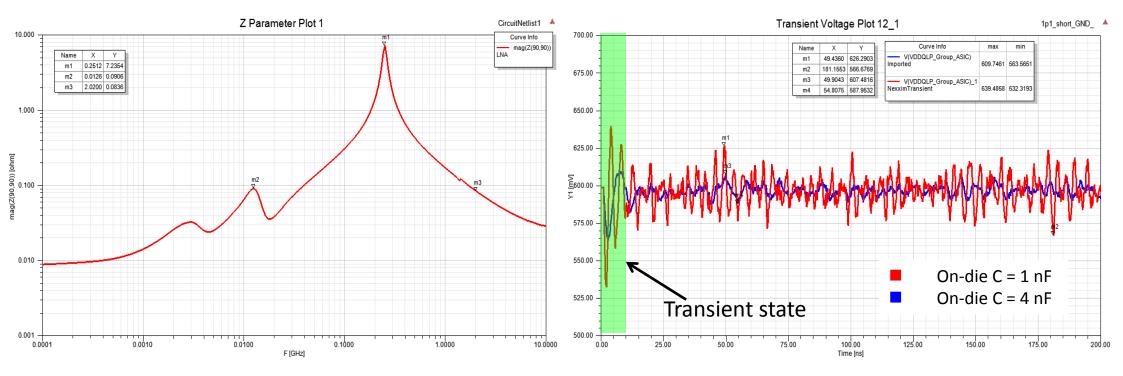
#### **DQ Read Mode**

Items	Byte 1	Byte 2	Byte 3	Byte 4	SPEC
DQ Skew+Jitter (ps)	78	76	94	82	-
DQS Jitter (ps)	12	12	12	12	-
TdIPW_total (UI)	0.67	0.68	0.6	0.65	0.45
TdIVW_total (UI)	0.31	0.36	0.25	0.34	0.25





## **VDDQLP**



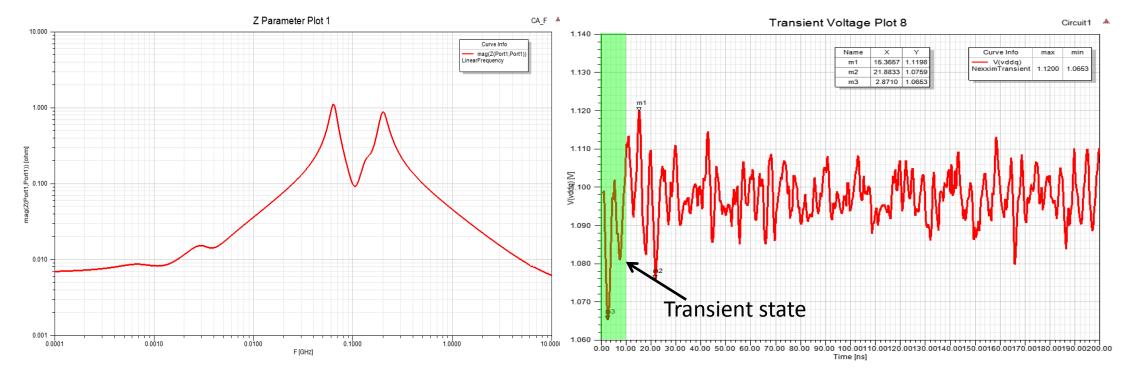
- Transient state (0 ~ 10ns):
  - On-die C => 1 nF: P2P Noise = 6.5% ~ -11.3%
  - On-die C => 4 nF: P2P Noise = 1.6% ~ -6%
- Steady state (10 ~ 200ns):
  - On-die C => 1 nF: P2P Noise = 4.3% ~ -4.7%
  - On-die C => 4 nF: P2P Noise = 1.1% ~ -2%

• SPEC: +/- 2.5% noise





# VDDQ\_DDR



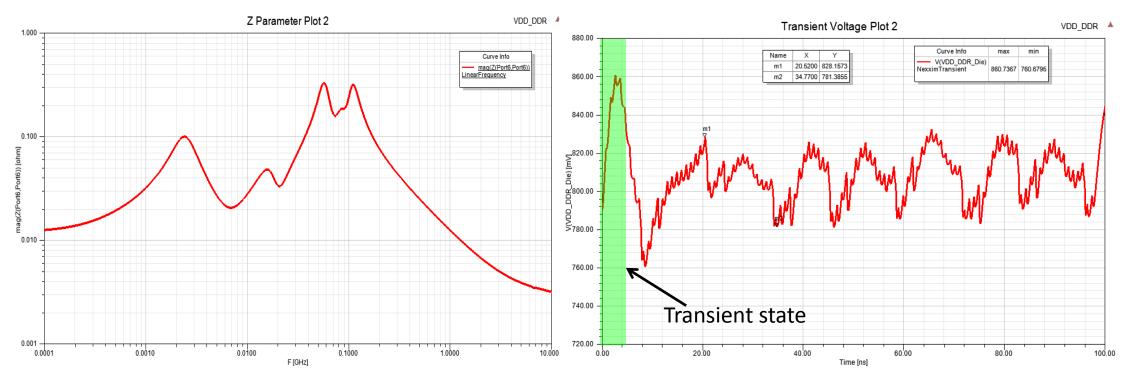
- Transient state (0 ~ 10ns):
  - On-die C => 3.6 nF: P2P Noise = 1.3% ~ -3.2%
- Steady state (10 ~ 200ns):
  - On-die C => 3.6 nF: P2P Noise = 1.8% ~ -2.2%

• SPEC: +/- 2.5% noise





# VDD\_DDR



- Transient state (0 ~ 10ns):
  - On-die C => 12nF: P2P Noise = 7.6% ~ -4.9%
- Steady state (10 ~ 200ns):
  - On-die C => 12 nF: P2P Noise = 3.5% ~ -2.4%

• SPEC: +/- 2% noise





# Suggestion

- > PCB routed skew limits:
  - ✓ Length control for each byte: 2mm





# **Thank You**

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